



ELECTRONICS, INC.
44 FARRAND STREET
BLOOMFIELD, NJ 07003
(973) 748-5089
<http://www.nteinc.com>

NTE2969

MOSFET

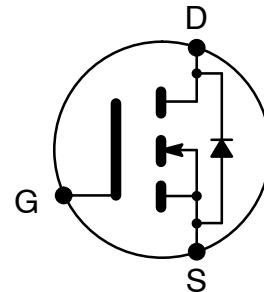
N-Channel, Enhancement Mode High Speed Switch TO3P Type Package

Description:

The NTE2969 is an N-channel enhancement mode power field effect transistor in a TO3P type package especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. This device is well suited for use in applications such as a high efficiency switch mode power supply or an electronic lamp ballast on half bridge.

Features:

- 30A, 400V, $R_{DS(on)} = 0.14\pm$ @ $V_{GS} = 10V$
- Low gate Charge (90nC Typ)
- Low C_{rss} (60pF Typ)
- Fast Switching
- 100% Avalanche Tested
- Improved dv/dt Capability



Absolute Maximum Ratings: ($T_C = +25^\circ C$ unless otherwise specified)

Drain-Source Voltage, V_{DSS}	400V
Drain Current, I_D Continuous	
$T_C = +25^\circ C$	30A
$T_C = +100^\circ C$	19A
Pulsed (Note 1)	120A
Gate-Source Voltage, V_{GS}	$\pm 30V$
Gate Current (Pulsed), I_{GM}	$\pm 1.5A$
Single Pulsed Avalanche Energy (Note 2), E_{AS}	1400mJ
Avalanche Current (Note 1), I_{AS}	30A
Repetitive Avalanche Energy (Note 1), E_{AR}	29mJ
Peak Diode Recovery dv/dt (Note 3), dv/dt	4.5V/ns
Total Power Dissipation ($T_C = +25^\circ C$), P_D	290W
Derate Above $25^\circ C$	$2.33W/^\circ C$
Operating Junction Temperature Range, T_J	-55° to +150°C
Storage Temperature Range, T_{stg}	-55° to +150°C
Maximum Lead Temperature (During Soldering, 1/8" from case, 5sec), T_L	+300°C
Thermal Resistance:	
Maximum Junction-to-Case, R_{thJC}	0.43°C/W
Typical Case-to-Sink, R_{thCS}	0.24°C/W
Maximum Junction-to-Ambient, R_{thJA}	40°C/W

Note 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Note 2. $L = 2.7mH$, $I_{AS} = 30A$, $V_{DD} = 50V$, $R_G = 27\pm$, Starting $T_J = +25^\circ C$.

Note 3. $I_{SD} \leq 30A$, $di/dt \leq 200A/\mu s$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = +25^\circ C$.

Electrical Characteristics: ($T_C = +25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
OFF Characteristics						
Drain–Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}$, $I_D = 250\text{mA}$	400	—	—	V
Breakdown Voltage Temperature Coefficient	$\Delta \text{BV}/\Delta T_J$	$I_D = 250\text{mA}$, Referenced to $+25^\circ\text{C}$	—	0.4	—	$\text{V}/^\circ\text{C}$
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 400\text{V}$, $V_{\text{GS}} = 0$	—	—	1	mA
		$V_{\text{DS}} = 320\text{V}$, $T_C = +125^\circ\text{C}$	—	—	10	mA
Gate–Source Leakage Forward	I_{GSSF}	$V_{\text{GS}} = 30\text{V}$, $V_{\text{DS}} = 0\text{V}$	—	—	100	nA
Gate–Source Leakage Reverse	I_{GSSR}	$V_{\text{GS}} = -30\text{V}$, $V_{\text{DS}} = 0\text{V}$	—	—	-100	nA
ON Characteristics						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}} = V_{\text{GS}}$, $I_D = 250\text{mA}$	3.0	—	5.0	V
Static Drain–Source ON Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}} = 10\text{V}$, $I_D = 12.5\text{A}$	—	0.107	0.14	\pm
Forward Transconductance	g_{fs}	$V_{\text{DS}} = 50\text{V}$, $I_D = 15\text{A}$, Note 4	—	20	—	mhos
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}$, $V_{\text{DS}} = 25\text{V}$, $f = 1\text{MHz}$	—	3400	4400	pF
Output Capacitance	C_{oss}		—	580	750	pF
Reverse Transfer Capacitance	C_{rss}		—	60	80	pF
Switching Characteristics						
Turn–On Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}} = 200\text{V}$, $I_D = 30\text{A}$, $R_G = 25\pm$, Note 4, Note 5	—	80	170	ns
Rise Time	t_r		—	320	650	ns
Turn–Off Delay Time	$t_{\text{d(off)}}$		—	190	390	ns
Fall Time	t_f		—	170	350	ns
Total Gate Charge	Q_g	$V_{\text{GS}} = 10\text{V}$, $I_D = 30\text{A}$, $V_{\text{DS}} = 320\text{V}$, Note 4, Note 5	—	90	120	nC
Gate–Source Charge	Q_{gs}		—	22	—	nC
Gate–Drain (“Miller”) Charge	Q_{gd}		—	46	—	nC
Source–Drain Diode Ratings and Characteristics						
Continuous Source Current	I_S	(Body Diode)	—	—	30	A
Pulse Source Current	I_{SM}	(Body Diode)	—	—	120	A
Diode Forward Voltage	V_{SD}	$I_S = 30\text{A}$, $V_{\text{GS}} = 0\text{V}$	—	—	1.5	V
Reverse Recovery Time	t_{rr}	$V_{\text{GS}} = 0\text{V}$, $I_S = 30\text{A}$, $dI_F/dt = 100\text{A}/\mu\text{s}$, Note 4	—	370	—	ns
Reverse Recovery Charge	Q_{rr}		—	3.9	—	μC

Note 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Note 4. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.

Note 5. Essentially independent of operating temperature.

